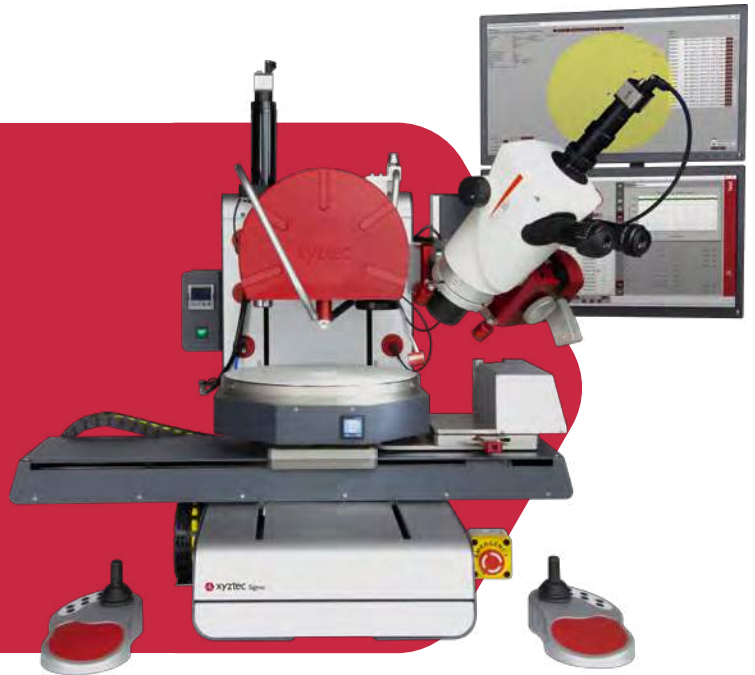


Sigma W12

Wafer bond tester



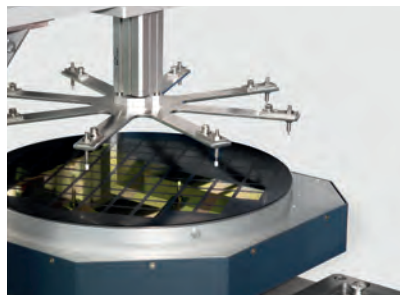
Bond tester for wafers 2 - 12 inch

- Wafers or at wafer level 2" - 12" (up to 300 mm)
- Precise testing and Cold Bump Pull (CBP) testing
- Large X/Y stages X: 600mm, Y: 370 mm
- Force range from 1 gf - 10 kgf
- Bump pitch down to 20 μ m



Panel chuck work holder

Vacuum work holder for panels or wafers up to 300 mm. Easily reach 100% of a 300 mm panel without repositioning your sample on the chuck.



Wafer pusher

In cases of extreme warpage, an optional wafer pusher ensures precise clamping.



Wafer cleaning unit

Keep test debris away from the wafer or the wafer chuck with a blower and vacuum cleaner or a roller with sticky foil, for pre- and post-cleaning.

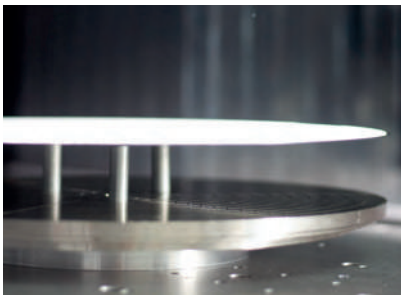
Sigma EFEM

Wafer/panel handler



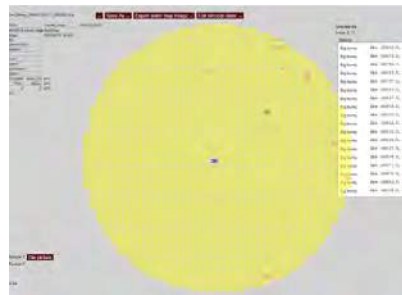
Chosen by the world's top 4 semiconductor packaging houses

Integration transforms the bond tester into a fully automated system. We offer various types of wafer and panel handlers (Equipment Front End Module), for operator-free bond testing.



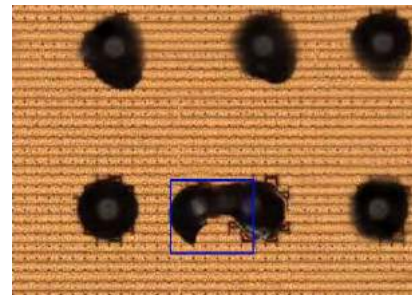
Intelligent lift pins

The system gently secures flat and warped wafers with the soft, flexible tips on the PID controlled wafer lift pins.



Substrate wafer map import

Easily import and export multiple file formats for wafer maps such as KLARF, (S)INF, G85, and others for full traceability. Defects or test positions are shown in an overview and are directly accessible for testing or analysis.



Big bump removal

Automatically shear the big bumps and clean the debris to prepare for wafer probing. Fully programmable vision algorithms can check if the removal of big bumps was successful.